

# **LOCTITE ABLESTIK 933-1**

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### PRODUCT DESCRIPTION

LOCTITE ABLESTIK 933-1 provides the following product characteristics:

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Technology	Ероху
Appearance	Black
Cure	Heat cure
Product Benefits	One component
	<ul> <li>Electrically Insulating</li> </ul>
	<ul> <li>Provides environmental and mechanical protection</li> </ul>
Application	Encapsulant
Application Method	Automatic dispenser

LOCTITE ABLESTIK 933-1 epoxy encapsulant is designed for encapsulating microelectronic chips. The low coefficient of thermal expansion minimizes stress effects on components and wiring during thermal shock tests.

LOCTITE ABLESTIK 933-1 encapsulant exhibits a longer work life and a lower moisture sensitivity than the anhydride-cured system.

### TYPICAL PROPERTIES OF UNCURED MATERIAL

Viscosity, Brookfield CP51, 25 °C, mPa·s (cP)	360,500
Density, g/cc	2.0
Work Life @ 25°C, days	61
Shelf Life @ ≥-40°C, days	365
Flash Point - See SDS	

# TYPICAL CURING PERFORMANCE

### **Recommended Curing Conditions**

2 hours @ 125°C

### **Alternative Curing Conditions**

30 minutes @ 150°C

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

### TYPICAL PROPERTIES OF CURED MATERIAL

# **Physical Properties**

Coefficient of Thermal Expansion TMA:		
Below Tg, ppm/°C		30
Above Tg, ppm/°C		100
Glass Transition Temperature (Tg), °C		124
Hardness, Shore D		92
Storage Modulus:		
@ -65°C	N/mm²	14,500
	(psi)	(2100×10 <sup>3</sup> )
@ 25°C	N/mm²	,
	(psi)	(1700×10³)
@ 150°C	N/mm²	345
	(psi)	(50×10³)

Extractable Ionic Content, ppm:	
Chloride (CI-)	300
Sodium (Na+)	55
Potassium (K+)	N/D
Water Extract Conductivity, µmhos/cm	290
Water Absorption, 24-hours, %	0.11
Specific Gravity	2.1
Weight Loss, %:	
@ 250°C	0.22
@ 300°C	0.67
Thermal Conductivity @ 121°C, W/(m-K)	1.0
Electrical Properties	
Volume Resistivity, ohms-cm	1×10 <sup>15</sup>
Dielectric Strength, volts/mil	1,000

### **GENERAL INFORMATION**

Dielectric Constant

Dissipation Factor

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

#### THAWING:

1. Allow container to reach room temperature before use.

## **DIRECTIONS FOR USE**

- Apply by syringe dispensing.
- 2. Cure at the recommended cure schedule.

### Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

#### Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

# Optimal Storage: -40 °C

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.



Conversions

 $(^{\circ}C \times 1.8) + 32 = ^{\circ}F$  $kV/mm \times 25.4 = V/mil$ mm / 25.4 = inches  $N \times 0.225 = Ib$  $N/mm \times 5.71 = Ib/in$  $N/mm^2 \times 145 = psi$  $MPa = N/mm^2$ MPa x 145 = psi N·m x 8.851 = lb·in  $N \cdot m \times 0.738 = lb \cdot ft$  $N \cdot mm \times 0.142 = oz \cdot in$ mPa·s = cP

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